

## Electronics Assembly Technologies Forum by Surface Mount Technology Association (SMTA)

Tuesday, 22 May 2018 | 08:30 – 17:00hrs

My1-4 (North Wing), Level 1A, MITEC | Kuala Lumpur, Malaysia

### Professional Development Course

|                    |  |
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| <b>08:30-12:00</b> | <b>Flip Chip, WLCSP, and FOWLP Assembly and Reliability</b><br>Dr. John LAU, Senior Technical Advisor, ASM Pacific Technology, Hong Kong |
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### Technical Program

|                    | Presentation Title  | Speaker   |
|--------------------|---|---|
| <b>13:30-14:00</b> | Versatility in X-ray Inspection for the Electronics Manufacturing Industry  | Mr. Steve HURSEY, Business Development Manager, Nordson Dage X-ray, UK                            |
| <b>14:00-14:30</b> | A Holistic Approach for Technology and Quality Audits in the New Era of Computer Servers Design and Manufacturing | Ms. Yvonne YEO Chii, Advisory Engineer, IBM Singapore Systems Supply Chain Engineering, Singapore |
| <b>14:30-15:00</b> | New LED Technology Challenges for X-Ray   | Mr. Justin KOW, Sales Manager, Feinfocus Product Line, YXLON International, Singapore             |
| <b>15:00-15:30</b> | Networking Break  |   |
| <b>15:30-16:00</b> | Impact of Stencil Quality on Solder Paste Printing Performance  | Mr. Jeffrey LEN, Senior Technical Support Engineer, Indium Corporation, Malaysia                  |
| <b>16:00-16:30</b> | PCB Surface Finishes & The Cleaning Process - A Compatibility Study   | Mr. Guan Tatt YEOH, Senior Application Engineer, ZESTRON Precision Cleaning Sdn Bhd, Malaysia     |
| <b>16:30-17:00</b> | Improving Automatic X-Ray Inspection Process with Artificial Intelligence   | Mr. Chwee Liong TEE, Senior Test Engineer, Intel Products (M) Sdn Bhd, Malaysia                   |
| <b>17:00</b>       | <b>Conference Conclusion</b>  |   |

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